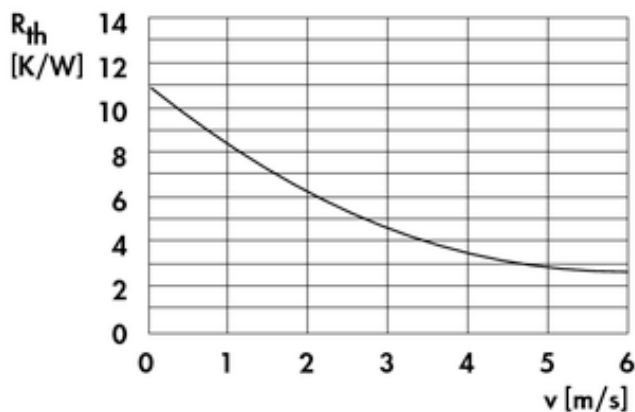
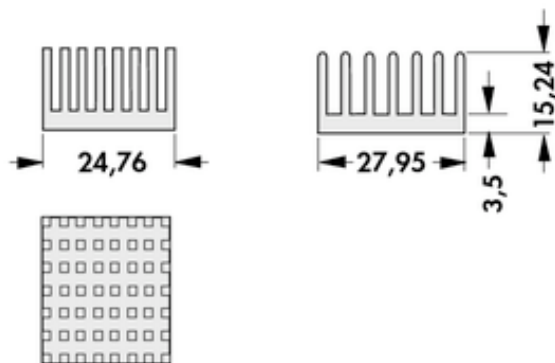
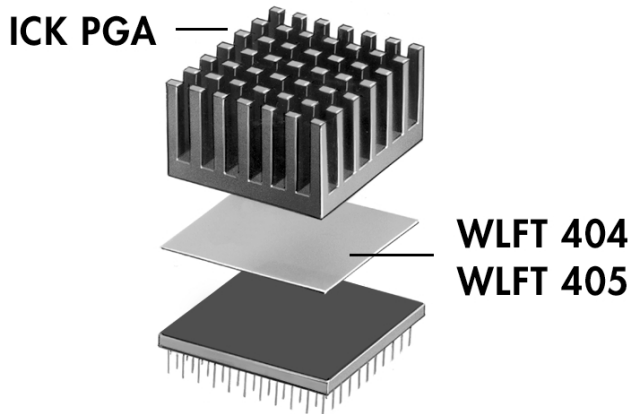


Heatsinks for PGA / **ICK PGA 11 x 11**



27,95 x 24,76 x 15,2 mm, for IC design PGA and others

**Parameters of article ICK PGA 11 x 11**

<b>R<sub>th</sub> [K/W]</b>	<b>i</b> 10.9
<b>dissipation loss [W]</b>	<b>i</b> 4.5
<b>mounting method</b>	therm. conductive foil / therm. cond. adhesive
<b>socket</b>	universal
<b>suitable for processor type</b>	universal
<b>width [mm]</b>	27.95
<b>height [mm]</b>	15.24
<b>plate thickness [mm]</b>	3.5
<b>length on stock [mm]</b>	24.76
<b>surface treatment</b>	black anodised

**Accessories/ related articles**

Thermally conductive foil both sides adhesive / **WLFT 404 24 x 27**

Thermally conductive foil both sides adhesive / **WLFT 405 24 x 27**